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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Active
Core Processor	S12Z
Core Size	16-Bit
Speed	50MHz
Connectivity	CANbus, LINbus, SCI, SPI
Peripherals	DMA, POR, PWM, WDT
Number of I/O	31
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	512 x 8
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	3.5V ~ 40V
Data Converters	A/D 9x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP Exposed Pad
Supplier Device Package	64-HLQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/s912zvml64f3mkh

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

- Internal 1 MHz RC oscillator (IRC)
- External 4-20 MHz crystal oscillator/resonator

1.4.3.2 Internal RC Oscillator (IRC)

- Trimmable internal 1MHz reference clock.
 - Trimmed accuracy over -40°C to 150°C junction temperature range: $\pm 1.3\%$ max.

1.4.4 Main External Oscillator (XOSCLCP)

- Amplitude controlled Pierce oscillator using 4 MHz to 20 MHz crystal
 - Current gain control on amplitude output
 - Signal with low harmonic distortion
 - Low power
 - Good noise immunity
 - Eliminates need for external current limiting resistor
 - Trans conductance sized for optimum start-up margin for typical crystals
 - Oscillator pins shared with GPIO functionality

1.4.5 Timer (TIM0)

- 4 x 16-bit channels Timer module for input capture or output compare
- 16-bit free-running counter with 8-bit precision prescaler

1.4.6 Timer (TIM1) (ZVMC256 only)

- 2 x 16-bit channels Timer module for input capture or output compare
- 16-bit free-running counter with 8-bit precision prescaler

1.4.7 Pulse width Modulator with Fault protection (PMF)

- 6 x 15-bit channel PWM resolution
- Each pair of channels can be combined to generate a PWM signal (with independent control of edges of PWM signal)
- Dead time insertion available for each complementary pair
- Center-aligned or edge-aligned outputs
- Programmable clock select logic with a wide range of frequencies
- Programmable fault detection

1.4.8 Programmable Trigger Unit (PTU)

• Enables synchronization between PMF and ADC

Chapter 2 Port Integration Module (S12ZVMPIMV3)

Global Address	Register Name		Bit 7	6	5	4	3	2	1	Bit 0
0x02F8–	Peserved	R	0	0	0	0	0	0	0	0
0x02FC	Reserved	W								
		R	0	0	0	0	0	0	0	
0x02FD	RDRP	W								RDRP0
0x02FE-	Decerved	R	0	0	0	0	0	0	0	0
0x0330	Reserved	W								
0.0224	DTII 2	R	0	0	0	0	0	0	0	PTIL0
0x0331	PIIL-	W								
	_	R	0	0	0	0	0	0	0	0
0x0332	Reserved	W								
	DTDOL ²	R	0	0	0	0	0	0	0	
0x0333	PTPSL ²	W								- PIPSL0
0.0004		R	0	0	0	0	0	0	0	
0x0334	PPSL ²	W								PPSL0
0,0225	Deserved	R	0	0	0	0	0	0	0	0
0x0335	Reserved	W								
	2	R	0	0	0	0	0	0	0	
0x0336	PIEL ²	W								PIEL0
00007	DIE! 2	R	0	0	0	0	0	0	0	
0x0337	PIFL ²	w								PIFL0

- One I-bit maskable interrupt vector request associated with \overline{IRQ} (at address vector base¹ + 0x0001D4).
- up to 113 additional I-bit maskable interrupt vector requests (at addresses vector base¹ + 0x000010 ... vector base + 0x0001D0).
- Each I-bit maskable interrupt request has a configurable priority level.
- I-bit maskable interrupts can be nested, depending on their priority levels.
- Wakes up the system from stop or wait mode when an appropriate interrupt request occurs or whenever $\overline{\text{XIRQ}}$ is asserted, even if X interrupt is masked.

4.1.3 Modes of Operation

• Run mode

This is the basic mode of operation.

• Wait mode

In wait mode, the INT module is capable of waking up the CPU if an eligible CPU exception occurs. Please refer to Section 4.5.3, "Wake Up from Stop or Wait Mode" for details.

• Stop Mode

In stop mode, the INT module is capable of waking up the CPU if an eligible CPU exception occurs. Please refer to Section 4.5.3, "Wake Up from Stop or Wait Mode" for details.

4.1.4 Block Diagram

Figure 4-1 shows a block diagram of the INT module.

5.1.2 Features

The BDC includes these distinctive features:

- Single-wire communication with host development system
- SYNC command to determine communication rate
- Genuine non-intrusive handshake protocol
- Enhanced handshake protocol for error detection and stop mode recognition
- Active out of reset in special single chip mode
- Most commands not requiring active BDM, for minimal CPU intervention
- Full global memory map access without paging
- Simple flash mass erase capability

5.1.3 Modes of Operation

S12 devices feature power modes (run, wait, and stop) and operating modes (normal single chip, special single chip). Furthermore, the operation of the BDC is dependent on the device security status.

5.1.3.1 BDC Modes

The BDC features module specific modes, namely disabled, enabled and active. These modes are dependent on the device security and operating mode. In active BDM the CPU ceases execution, to allow BDC system access to all internal resources including CPU internal registers.

5.1.3.2 Security and Operating mode Dependency

In device run mode the BDC dependency is as follows

- Normal modes, unsecure device General BDC operation available. The BDC is disabled out of reset.
- Normal modes, secure device BDC disabled. No BDC access possible.
- Special single chip mode, unsecure BDM active out of reset. All BDC commands are available.
- Special single chip mode, secure BDM active out of reset. Restricted command set available.

When operating in secure mode, BDC operation is restricted to allow checking and clearing security by mass erasing the on-chip flash memory. Secure operation prevents BDC access to on-chip memory other than mass erase. The BDC command set is restricted to those commands classified as Always-available.

Field	Description
7 ARM	 Arm Bit — The ARM bit controls whether the DBG module is armed. This bit can be set and cleared by register writes and is automatically cleared when the state sequencer returns to State0 on completing a debugging session. On setting this bit the state sequencer enters State1. 0 Debugger disarmed. No breakpoint is generated when clearing this bit by software register writes. 1 Debugger armed
6 TRIG	 Immediate Trigger Request Bit — This bit when written to 1 requests an immediate transition to final state independent of comparator status. This bit always reads back a 0. Writing a 0 to this bit has no effect. 0 No effect. 1 Force state sequencer immediately to final state.
4 BDMBP	 Background Debug Mode Enable — This bit determines if a CPU breakpoint causes the system to enter Background Debug Mode (BDM) or initiate a Software Interrupt (SWI). If this bit is set but the BDC is not enabled, then no breakpoints are generated. 0 Breakpoint to Software Interrupt if BDM inactive. Otherwise no breakpoint. 1 Breakpoint to BDM, if BDC enabled. Otherwise no breakpoint.
3 BRKCPU	CPU Breakpoint Enable — The BRKCPU bit controls whether the debugger requests a breakpoint to CPU upon transitions to State0. If tracing is enabled, the breakpoint is generated on completion of the tracing session. If tracing is not enabled, the breakpoint is generated immediately. Please refer to Section 6.4.7 for further details. 0 Breakpoints disabled 1 Breakpoints enabled
1–0 EEVE	External Event Enable — The EEVE bits configure the external event function. Table 6-5 explains the bit encoding.

Table 6-4. DBGC1 Field Descriptions

Table 6-5. EEVE Bit Encoding

EEVE	Description
00	External event function disabled
01	External event forces a trace buffer entry if tracing is enabled
10	External event is mapped to the state sequencer, replacing comparator channel 3
11	External event pin gates trace buffer entries

6.3.2.2 Debug Control Register2 (DBGC2)

Address: 0x0101



Figure 6-4. Debug Control Register2 (DBGC2)

Read: Anytime.

Write: Anytime the module is disarmed and PTACT is clear.

This register configures the comparators for range matching.

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Chapter 6 S12Z Debug (S12ZDBG) Module

The number of core clock cycles since the last entry equals the timestamp + 1. The core clock runs at twice the frequency of the bus clock. The timestamp of the first trace buffer entry is 0x0000. With timestamps enabled trace buffer entries are initiated in the following ways:

- according to the trace mode specification, for example COF PC addresses in Normal mode
- on a timestamp counter overflow If the timestamp counter reaches 0xFFFF then a trace buffer entry is made, with timestamp= 0xFFFF and the timestamp overflow bit TOVF is set.
- on a match of comparator D

If STAMP and DSTAMP are set then comparator D is used for forcing trace buffer entries with timestamps. The state control register settings determine if comparator D is also used to trigger the state sequencer. Thus if the state control register configuration does not use comparator D, then it is used solely for the timestamp function. If comparator D initiates a timestamp then the CTI bit is set in the INFO byte. This can be used in Normal/Loop1 mode to indicate when a particular data access occurs relative to the PC flow. For example when the timing of an access may be unclear due to the use of indexes.

NOTE

If comparator D is configured to match a PC address then associated timestamps trigger a trace buffer entry during execution of the previous instruction. Thus the PC stored to the trace buffer is that of the previous instruction. The comparator must contain the PC address of the instruction's first opcode byte

Timestamps are disabled in Pure PC mode.

6.4.5.4 Reading Data from Trace Buffer

The data stored in the trace buffer can be read using either the background debug controller (BDC) module or the CPU provided the DBG module is not armed and is configured for tracing by TSOURCE. When the ARM bit is set the trace buffer is locked to prevent reading. The trace buffer can only be unlocked for reading by an aligned word write to DBGTB when the module is disarmed. The trace buffer can only be read through the DBGTB register using aligned word reads. Reading the trace buffer while the DBG module is armed, or trace buffer locked returns 0xEE and no shifting of the RAM pointer occurs. Any byte or misaligned reads return 0xEE and do not cause the trace buffer pointer to increment to the next trace buffer address.

Reading the trace buffer is prevented by internal hardware whilst profiling is active because the RAM pointer is used to indicate the next row to be transmitted. Thus attempted reads of DBGTB do not return valid data when the PTACT bit is set. To initialize the pointer and read profiling data, the PTACT bit must be cleared and remain cleared.

The trace buffer data is read out first-in first-out. By reading CNT in DBGCNT the number of valid 64-bit lines can be determined. DBGCNT does not decrement as data is read.

Whilst reading, an internal pointer is used to determine the next line to be read. After a tracing session, the pointer points to the oldest data entry, thus if no overflow has occurred, the pointer points to line0. The

- Frequency trimming (A factory trim value for 1MHz is loaded from Flash Memory into the IRCTRIM register after reset, which can be overwritten by application if required)
- Temperature Coefficient (TC) trimming. (A factory trim value is loaded from Flash Memory into the IRCTRIM register to turn off TC trimming after reset. Application can trim the TC if required by overwriting the IRCTRIM register).

Other features of the S12CPMU_UHV_V10_V6 include

- Oscillator clock monitor to detect loss of crystal
- Autonomous periodical interrupt (API)
- Bus Clock Generator
 - Clock switch to select either PLLCLK or external crystal/resonator based Bus Clock
 - PLLCLK divider to adjust system speed
- System Reset generation from the following possible sources:
 - Power-on reset (POR)
 - Low-voltage reset (LVR)
 - COP system watchdog, COP reset on time-out, windowed COP
 - Loss of oscillation (Oscillator clock monitor fail)
 - Loss of PLL clock (PLL clock monitor fail)
 - External pin RESET

8.3.2.6 S12CPMU_UHV_V10_V6 Post Divider Register (CPMUPOSTDIV)

The POSTDIV register controls the frequency ratio between the VCOCLK and the PLLCLK.

Module Base + 0x0006





Read: Anytime

Write: If PLLSEL=1 write anytime, else write has no effect

If PLL is locked (LOCK=1) $f_{PLL} = \frac{f_{VCO}}{(POSTDIV + 1)}$ If PLL is not locked (LOCK=0) $f_{PLL} = \frac{f_{VCO}}{4}$ If PLL is selected (PLLSEL=1) $f_{bus} = \frac{f_{PLL}}{2}$

When changing the POSTDIV[4:0] value or PLL transitions to locked stated (lock=1), it takes up to 32 Bus Clock cycles until f_{PLL} is at the desired target frequency. This is because the post divider gradually changes (increases or decreases) f_{PLL} in order to avoid sudden load changes for the on-chip voltage regulator.

8.3.2.7 S12CPMU_UHV_V10_V6 Interrupt Flags Register (CPMUIFLG)

This register provides S12CPMU_UHV_V10_V6 status bits and interrupt flags.

9.3.1 Modes of Operation

9.3.1.1 Conversion Modes

This architecture provides single, multiple, or continuous conversion on a single channel or on multiple channels based on the Command Sequence List.

9.3.1.2 MCU Operating Modes

• MCU Stop Mode

Before issuing an MCU Stop Mode request the ADC should be idle (no conversion or conversion sequence or Command Sequence List ongoing).

If a conversion, conversion sequence, or CSL is in progress when an MCU Stop Mode request is issued, a Sequence Abort Event occurs automatically and any ongoing conversion finish. After the Sequence Abort Event finishes, if the STR_SEQA bit is set (STR_SEQA=1), then the conversion result is stored and the corresponding flags are set. If the STR_SEQA bit is cleared (STR_SEQA=0), then the conversion result is not stored and the corresponding flags are not set. The microcontroller then enters MCU Stop Mode without SEQAD_IF being set. Alternatively, the Sequence Abort Event can be issued by software before an MCU Stop Mode request. As soon as flag SEQAD_IF is set the MCU Stop Mode request can be is issued. With the occurrence of the MCU Stop Mode Request until exit from Stop Mode all flow control signals (RSTA, SEQA, LDOK, TRIG) are cleared.

After exiting MCU Stop Mode, the following happens in the order given with expected event(s) depending on the conversion flow control mode:

- In ADC conversion flow control mode "Trigger Mode" a Restart Event is expected to simultaneously set bits TRIG and RSTA, causing the ADC to execute the Restart Event (CMD_IDX and RVL_IDX cleared) followed by the Trigger Event. The Restart Event can be generated automatically after exit from MCU Stop Mode if bit AUT_RSTA is set.
- In ADC conversion flow control mode "Restart Mode", a Restart Event is expected to set bit RSTA only (ADC already aborted at MCU Stop Mode entry hence bit SEQA must not be set simultaneously) causing the ADC to execute the Restart Event (CDM_IDX and RVL_IDX cleared). The Restart Event can be generated automatically after exit from MCU Stop Mode if bit AUT_RSTA is set.
- The RVL buffer select (RVL_SEL) is not changed if a CSL is in process at MCU Stop Mode request. Hence the same buffer will be used after exit from Stop Mode that was used when the Stop Mode request occurred.

Chapter 15 Pulse Width Modulator with Fault Protection (PMF15B6CV4)



NOTE

The waveform at the output is delayed by two core clock cycles for deadtime insertion.

15.4.6 Top/Bottom Correction

In complementary mode, either the top or the bottom transistor controls the output voltage. However, deadtime has to be inserted to avoid overlap of conducting interval between the top and bottom transistor. Both transistors in complementary mode are off during deadtime, allowing the output voltage to be determined by the current status of the load and introduce distortion in the output voltage. See Figure 15-54. On AC induction motors running open-loop, the distortion typically manifests itself as poor low-speed performance, such as torque ripple and rough operation.

16.3.2.9 SCI Data Registers (SCIDRH, SCIDRL)

Module Base + 0x0006



Figure 16-12. SCI Data Registers (SCIDRH)

Module Base + 0x0007

	7	6	5	4	3	2	1	0
R	R7	R6	R5	R4	R3	R2	R1	R0
W	T7	Т6	T5	T4	Т3	T2	T1	T0
Reset	0	0	0	0	0	0	0	0

Figure 16-13. SCI Data Registers (SCIDRL)

Read: Anytime; reading accesses SCI receive data register

Write: Anytime; writing accesses SCI transmit data register; writing to R8 has no effect

NOTE

The reserved bit SCIDRH[2:0] are designed for factory test purposes only, and are not intended for general user access. Writing to these bit is possible when in special mode and can alter the modules functionality.

Table 16-13. SCIDRH and SCIDRL Field Descriptions

Field	Description
SCIDRH 7 R8	Received Bit 8 — R8 is the ninth data bit received when the SCI is configured for 9-bit data format (M = 1).
SCIDRH 6 T8	Transmit Bit 8 — T8 is the ninth data bit transmitted when the SCI is configured for 9-bit data format (M = 1).
SCIDRL 7:0 R[7:0] T[7:0]	 R7:R0 — Received bits seven through zero for 9-bit or 8-bit data formats T7:T0 — Transmit bits seven through zero for 9-bit or 8-bit formats

NOTE

If the value of T8 is the same as in the previous transmission, T8 does not have to be rewritten. The same value is transmitted until T8 is rewritten

In 8-bit data format, only SCI data register low (SCIDRL) needs to be accessed.

16.5.3.1.6 RXEDGIF Description

The RXEDGIF interrupt is set when an active edge (falling if RXPOL = 0, rising if RXPOL = 1) on the RXD pin is detected. Clear RXEDGIF by writing a "1" to the SCIASR1 SCI alternative status register 1.

16.5.3.1.7 BERRIF Description

The BERRIF interrupt is set when a mismatch between the transmitted and the received data in a single wire application like LIN was detected. Clear BERRIF by writing a "1" to the SCIASR1 SCI alternative status register 1. This flag is also cleared if the bit error detect feature is disabled.

16.5.3.1.8 BKDIF Description

The BKDIF interrupt is set when a break signal was received. Clear BKDIF by writing a "1" to the SCIASR1 SCI alternative status register 1. This flag is also cleared if break detect feature is disabled.

16.5.4 Recovery from Wait Mode

The SCI interrupt request can be used to bring the CPU out of wait mode.

16.5.5 Recovery from Stop Mode

An active edge on the receive input can be used to bring the CPU out of stop mode.

18.3.2.13 GDU Phase Log Register (GDUPHL)



1. Read: Anytime Write: never

Table 18-16. GDU Phase Log Register Field Descriptions

Field	Description
2:0 GPHL	GDU Phase Log Bits— If a desaturation error occurs the phase status bits GPHS[2:0] in register GDUSTAT are copied to this register. The GDUPHL register is cleared only on reset. See Section 18.4.5, "Desaturation Error

18.3.2.14 GDU Clock Control Register 2 (GDUCLK2)



1. Read: Anytime

Write: Only if GWP=0

Table 18-17. GDUCLK2 Register Field Descriptions

Field	Description
3-0 GCPCD[3:0]	GDU Charge Pump Clock Divider — These bits select the clock divider factor which is used to divide down the bus clock frequency f_{BUS} for the charge pump clock f_{CP} . See Table 18-18 for divider factors. These bits cannot be modified after GWP bit is set. See also Section 18.4.4, "Charge Pump

NOTE

The GCPCD bits must be set to the required value before GCPE bit is set. If a different charge pump clock frequency is required GCPE has to be cleared before new values to GCPCD bits are written.



1: Flag cleared, transmitter re-enable not successful because over-current is still present

2: Flag cleared, transmitter re-enable not successful because LPTxD is dominant

3: Flag cleared, transmitter re-enable successful

Figure 19-12. Overcurrent interrupt handling

19.4.4.2 TxD-dominant timeout Interrupt

NOTE

In order to perform PWM communication, the TxD-dominant timeout feature must be disabled.

To protect the LIN bus from a network lock-up, the LIN Physical Layer implements a TxD-dominant timeout mechanism. When the LPTxD signal has been dominant for more than t_{DTLIM} the transmitter is disabled and the LPDT status flag and the LPDTIF interrupt flag are set.

In order to re-enable the transmitter again, the following prerequisites must be met:

1) TxD-dominant condition is over (LPDT=0)

2) LPTxD is recessive or the LIN Physical Layer is in shutdown or receive only mode for a minimum of a transmit bit time



Figure 20-1. FTMRZ Block Diagram (Single P-Flash Block plus EEPROM block)

$$\mathsf{T}_{\mathsf{J}} = \mathsf{T}_{\mathsf{A}} + (\mathsf{P}_{\mathsf{D}} \bullet \Theta_{\mathsf{J}} \mathsf{A})$$

 T_J = Junction Temperature, [°C] T_A = Ambient Temperature, [°C] P_D = Total Chip Power Dissipation, [W] Θ_{IA} = Package Thermal Resistance, [°C/W]

The total power dissipation P_D can be calculated from the equation below. Table A-7 below lists the power dissipation components. Figure A-2 provides an overview of power pin connectivity.

 $P_{D} = P_{VSUP} + P_{BCTL} + P_{INT} - P_{GPIO} + P_{LIN} - P_{EVDD1} + P_{GDU}$

Power Component	Description
P _{VSUP} = V _{SUP} I _{SUP}	Internal Power through VSUP pin
P _{BCTL} = V _{BCTL} I _{BCTL}	Internal Power through BCTL pin
$P_{INT} = V_{DDX} I_{VDDX} + V_{DDA} I_{VDDA}$	Internal Power through VDDX/A pins.
$P_{GPIO} = V_{I/O} I_{I/O}$	Power dissipation of external load driven by GPIO Port. Assuming the load is connected between GPIO and ground. This power component is included in P_{INT} and is subtracted from overall MCU power dissipation P_{D}
$P_{LIN} = V_{LIN} I_{LIN}$	Power dissipation of LINPHY
$P_{GDU}^{(1)} = (-V_{VLS_OUT} I_{VLS_OUT}) + (V_{VBS} I_{VBS}) + (V_{VCP}I_{VCP}) + (V_{VI} S_n I_{VI} S_n)$	Power dissipation of FET-Predriver without the outputs switching

Table A-7. Power Dissipation Components

1. No switching. GDU power consumption is very load dependent.

H.3 Dynamic Electrical Characteristics

Table H-3. Dynamic Electrical Characteristics

Chara noted	cteristics noted under conditions $5.5V \le VSUP \le 18$ V, -40 reflect the approximate parameter mean at T_A = 25°C und	$^{\circ}C \le T_{J} \le 17$	5°C unless onditions un	otherwise no less otherw	oted. Typica ⁄ise noted.	l values
Num	Ratings	Symbol	Min	Тур	Max	Unit
	SIGNAL EDGE RISE AND FAL	L TIMES (CA	ANH, CANL)	I	
1	Propagation Loop Delay TXD to RXD (Recessive to Dominant) Slew Rate 6 Slew Rate 5 Slew Rate 4 Slew Rate 2 Slew Rate 1 Slew Rate 0	t _{LRD}	_	146 112 89 83 72 64	(255)	ns
2	Propagation Delay TXD to CAN (Recessive to Dominant) Slew Rate 6 Slew Rate 5 Slew Rate 4 Slew Rate 2 Slew Rate 1 Slew Rate 0	t _{TRD}	_	98 63 43 38 28 23	_	ns
3	Propagation Delay CAN to RXD (Recessive to Dominant, using slew rate 0)	t _{RRD}	—	42	_	ns
4	Propagation Loop Delay TXD to RXD (Dominant to Recessive) Slew Rate 6 Slew Rate 5 Slew Rate 4 Slew Rate 2 Slew Rate 1 Slew Rate 0	t _{LDR}	_	366 224 153 139 114 102	(255)	ns
5	Propagation Delay TXD to CAN (Dominant to Recessive) Slew Rate 6 Slew Rate 5 Slew Rate 4 Slew Rate 2 Slew Rate 1 Slew Rate 0	t _{TDR}	_	280 152 90 81 56 46	_	ns
6	Propagation Delay CAN to RXD (Dominant to Recessive, using slew rate 0)	t _{RDR}	_	56	_	ns

K.4 80LQFP-EP Mechanical Information

Figure K-4. 80LQFP-EP



Appendix M Detailed Register Address Map

M.3 0x0070-0x00FF S12ZMMC

Address	Name		Bit 7	6	5	4	3	2	1	Bit 0	
0x0070	MODE	R	MODC	0	0	0	0	0	0	0	
		W									
0x0071-	Reserved	R	0	0	0	0	0	0	0	0	
0x007F		W									
0x0080	MMCECH	R W		ITR[3	3:0]			TGT	[3:0]		
0x0081	MMCECL	R W		ACC[3:0]			ERR	[3:0]		
0x0082	MMCCCRH	R	CPUU	0	0	0	0	0	0	0	
		w									
0x0083	MMCCCRL	R	0	CPUX	0	CPUI	0	0	0	0	
		w									
		_ [
0x0084	Reserved	R	0	0	0	0	0	0	0	0	
		···[
0x0085	MMCPCH	5 MMCPCH	R				CPUPC[23:	16]			
		••									
0x0086	MMCPCM	R				CPUPC[15	:8]				
		w									
0x0087	MMCPCL	R				CPUPC[7:	0]				
		W									
0x0088-	Reserved	R	0	0	0	0	0	0	0	0	
0x00FF		W									

M.4 0x0100-0x017F S12ZDBG

Address	Name		Bit 7	6	5	4	3	2	1	Bit 0
0x0100	DBGC1	R W	ARM	0 TRIG	reserved	BDMBP	BRKCPU	reserved	EEVE1	EEVE0 ²
0v0101	DBGC2	R	0	0	0	0				
0x0101		W W	W					CDCIW		ADCIVI
		-								
0x0102	DBGTCRH 2	R W	reserved	TSOURCE	TRANGE		TRCI	MOD	TAL	IGN

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Global Address	Register Name		Bit 7	6	5	4	3	2	1	Bit 0
0x0338– 0x0339	Reserved	R	0	0	0	0	0	0	0	0
		W								
0x033A	PTABYPL ²	R	0	0	0	0	0	0	0	PTABYPL0
		W								
0x033B	PTADIRL ²	R	0	0	0	0	0	0	0	PTADIRL0
		W								
0x033C	DIENL ²	R	0	0	0	0	0	0	0	
		W								DIENLU
0x033D	PTAENL ²	R	0	0	0	0	0	0	0	
		W								PIAENLO
0x033E	PIRL ²	R	0	0	0	0	0	0	0	PIRL0
		w								
0x033F	PTTEL ²	R	0	0	0	0	0	0	0	PTTEL0
		W								

1. Only available for ZVML128, ZVML64, ZVML32, and ZVML31

2. Only available for ZVMC256

3. PWMPRR[1] only writable for ZVMC256

4. Only available for ZVMC256, ZVML31, ZVM32, ZVM16

5. Not available for ZVMC256

M.6 0x0380-0x039F FTMRZ128K512

Address	Name		7	6	5	4	3	2	1	0
0x0380	FCLKDIV	R W	FDIVLD	FDIVLCK	FDIV5	FDIV4	FDIV3	FDIV2	FDIV1	FDIV0
0x0381	FSEC	R W	KEYEN1	KEYEN0	RNV5	RNV4	RNV3	RNV2	SEC1	SEC0
0x0382	FCCOBIX	R	0	0	0	0	0	CCOBIX2	CCOBIX1	CCOBIX0
		W								
0x0383	FPSTAT									MOTAT
		R	FPOVRD	0	0	0	0	0	0	ACK
		W								

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